

ASI Project 1-A026: A high efficiency, integrated solar module on a transparent substrate

Grant to Sapphicon Semiconductor, part of the Silanna Group



Acknowledgement

The Australian Solar Institute

Silanna engineers, technicians and operators

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Chris Escott

Matthew Godfrey



Introduction to Silanna

■ Silicon technologies

- Silicon CMOS
- Thin film silicon on sapphire
- 0.25 μ m FEOL, 0.50 μ m BEOL

■ Cleanrooms

- Class 10 Cleanroom, 460m²
- Class 1 Cleanroom, 460m²

■ Installed Capacity

- 1,500 6" wafers/month (full loop)
- Low to medium volume production
- R&D support

■ Nitride technology (in development)

- III-Nitrides (2, 4, 6 and 8" capable)

■ Cleanrooms

- Class 10 Cleanroom, 435m²

■ Installed capacity

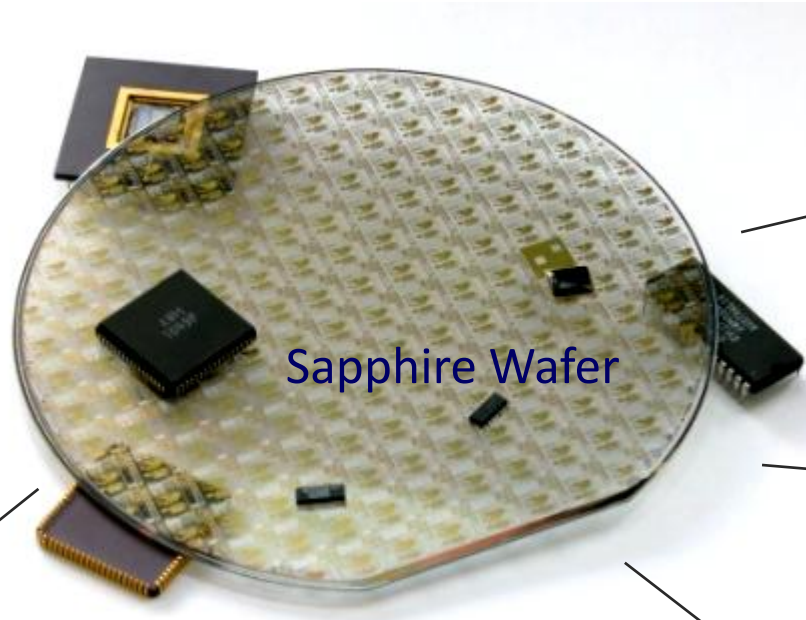
- Over 400 6" epi-wafers per month
(Over 5,000 2" epiwafers per month)

>20 years at Sydney's Olympic Park





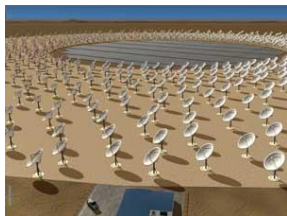
Silanna Silicon-on-Sapphire



Mobile Base Stations



Satellites



Radio Astronomy



Digital TV Tuners



Addressable CATV Taps



Mobile Phones



Low Noise Blockers



Project objectives

Develop thin-film, single-crystal silicon solar cells

Milestone 1:

17% efficiency under field realistic conditions
by end of October 2010

Milestone 2:

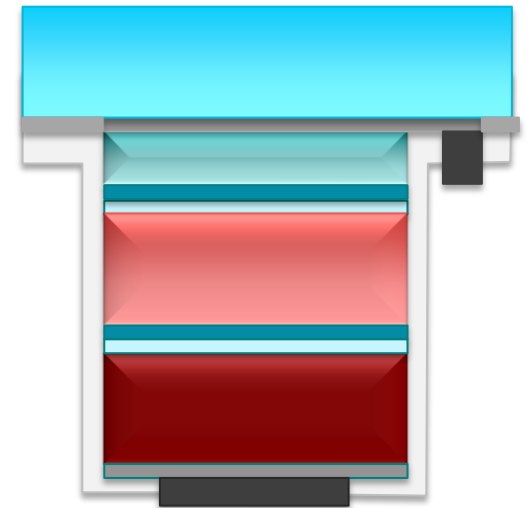
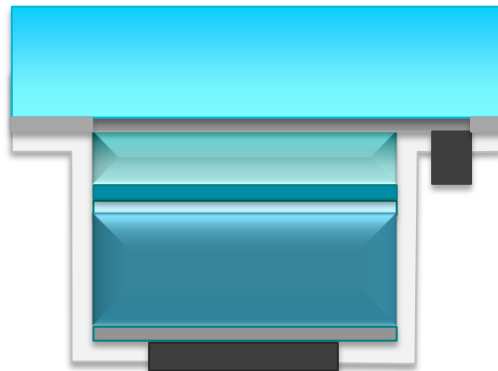
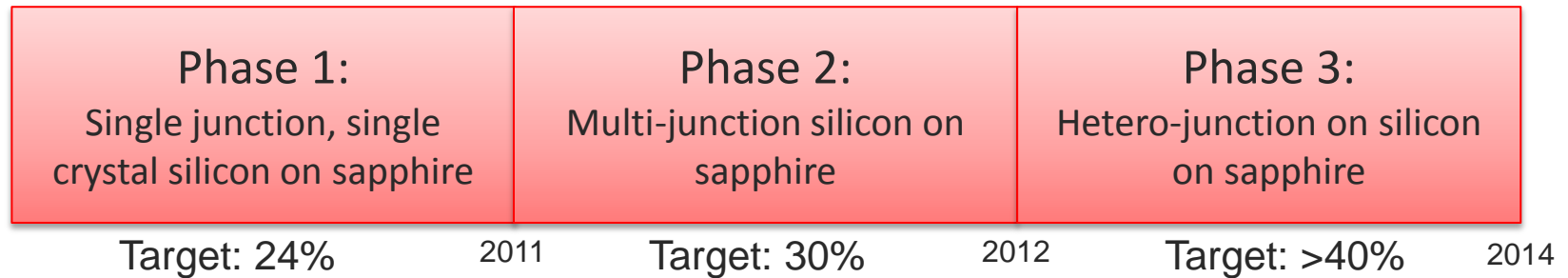
22% efficiency under field realistic conditions
by end of September 2011

A one-year feasibility study of a new solar cell ...



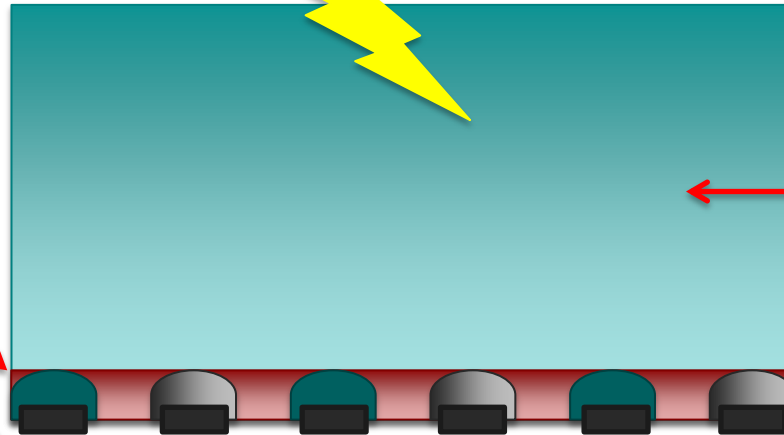
Silanna's Program Objectives (4 years)

Commercialize robust, high efficiency, low cost cells and modules for concentrating photovoltaic systems





Cell #1 - A silicon-on-sapphire solar cell



Silicon
*Excellent crystal quality
No shadowing
Low series resistance
High collection efficiency*

Sapphire
*Robust
Transparent
Good thermal conductor*

Space



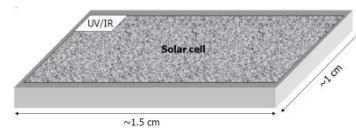
*Radiation hard
Trusted technology*

Concentrating PV



*Reduced efficiency loss
Adaptive control
Simpler solution than III-V*

Self-powered circuits

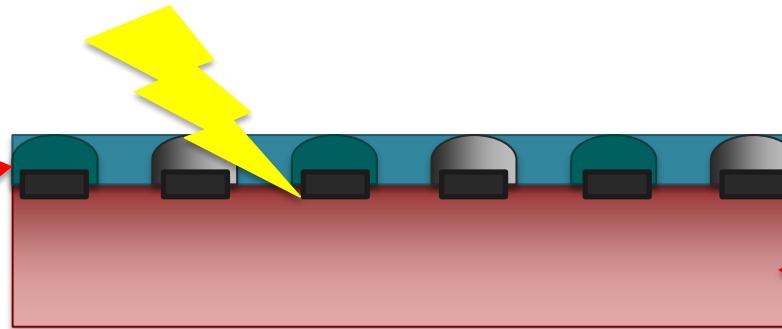


*Self-powered sensors,
actuators, etc.*



Cell #2 - Post-growth layer transfer solar cell

Silicon
*Excellent crystal quality
No shadowing
Low series resistance
High collection efficiency*



Handle wafer
*Mechanical support
Heat sink
Integrated electronics*



Space



*Radiation hard
Trusted technology*



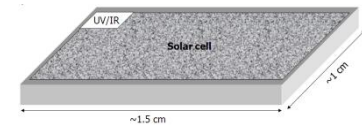
Concentrating PV



*Reduced efficiency loss
Adaptive control
Simpler solution than III-V*



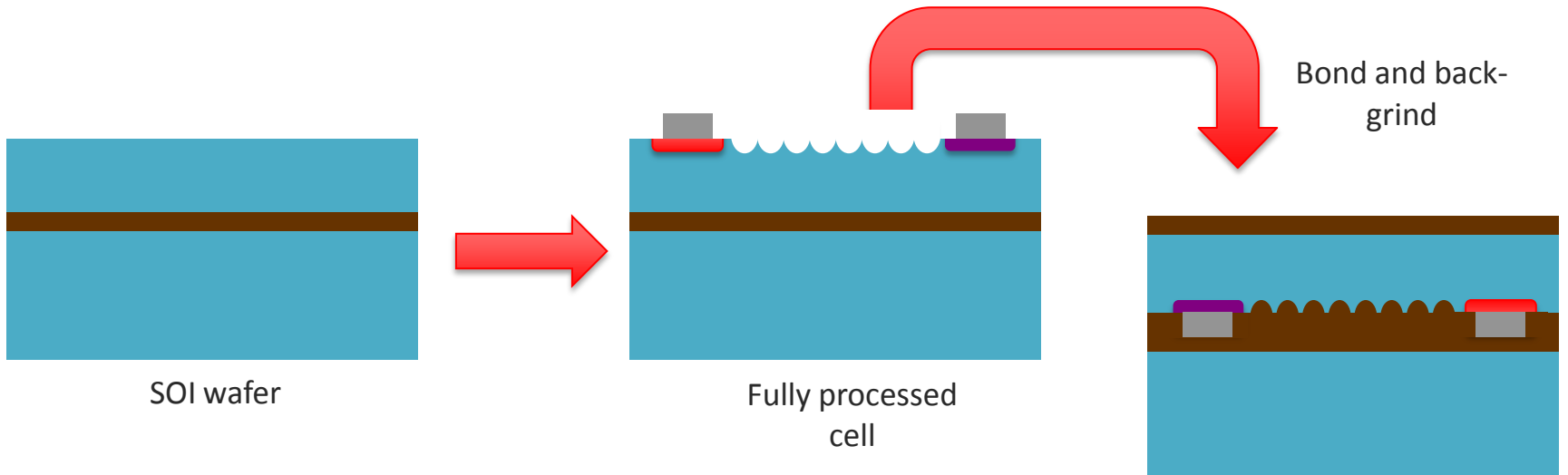
Self-powered circuits



*Self-powered sensors,
actuators, etc.*



Fabricating the post-growth layer transfer cell



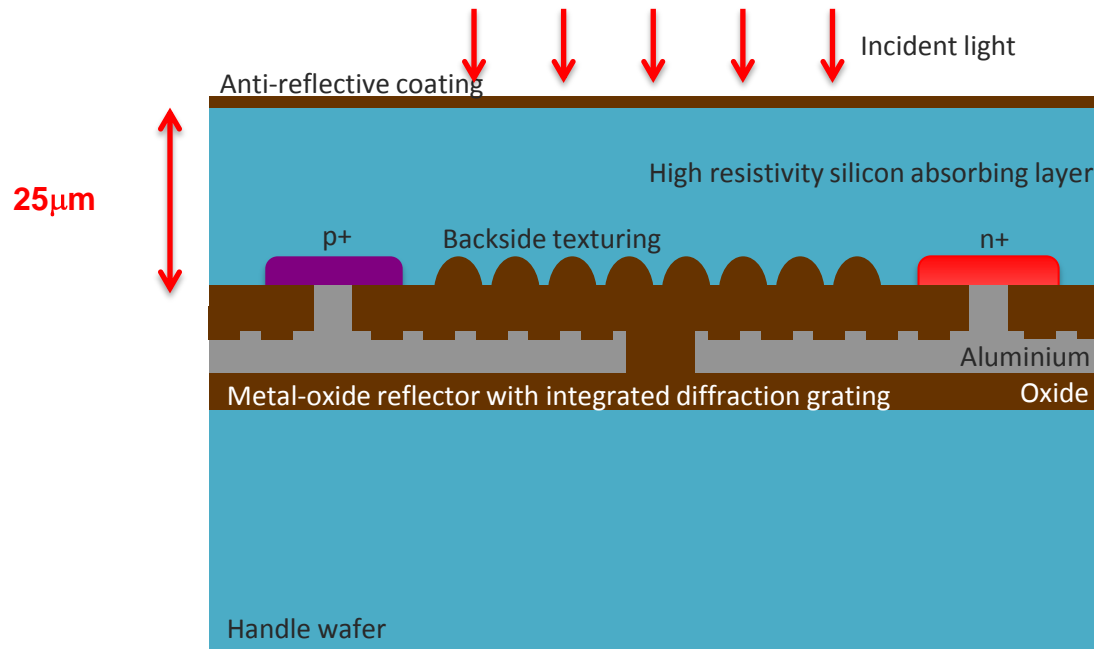


Experimental setup

- Experiments undertaken: 91 6" wafers processed at Silanna's Fab
 1. **Surface passivation:** PECVD silicon nitride, thermal silicon nitride, alumina, thermal (dry) silicon dioxide, wet silicon dioxide, field passivation (doped via diffusion and implantation)
 2. **Light trapping:** Wafer-bonding, metal-oxide reflectors, DBRs, surface texturing through isotropic and anisotropic etching, diffraction grating
 3. **Cell design:** pitch, size, finger orientation, thickness
 4. **Contacts:** implant dose and energy, MIS contacts
 5. **Materials:** FZ vs CZ, resistivity, vendor
 6. **Processes:** order and optimisation
 7. **Cell isolation:** etch, shadow, spot size
 8. **Measurement:** quantum efficiency, solar simulator (CW and flash), concentration
- Measurement and characterizations performed at
 - Silanna
 - SUNLab at University of Ottawa, Canada
 - Fraunhofer ISE in Freiburg, Germany
- TCAD simulation (Synopsys Sentaurus) used extensively for virtual experimentation

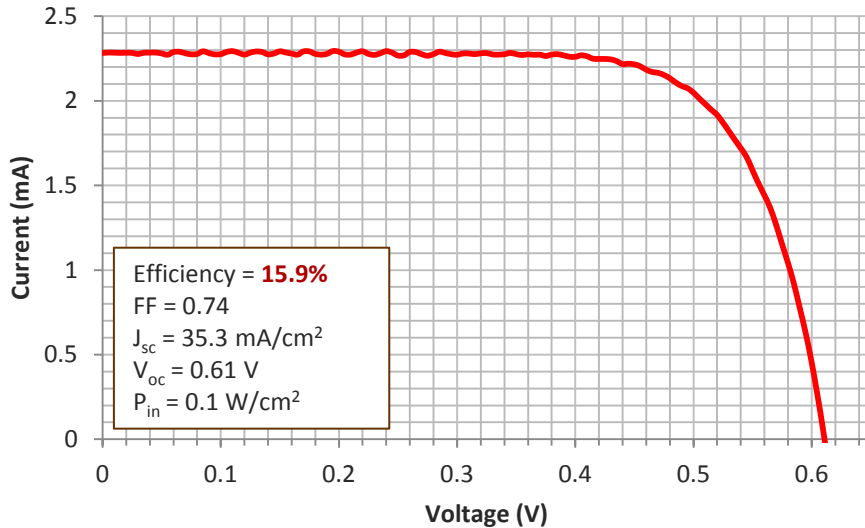


Optimal cell architecture

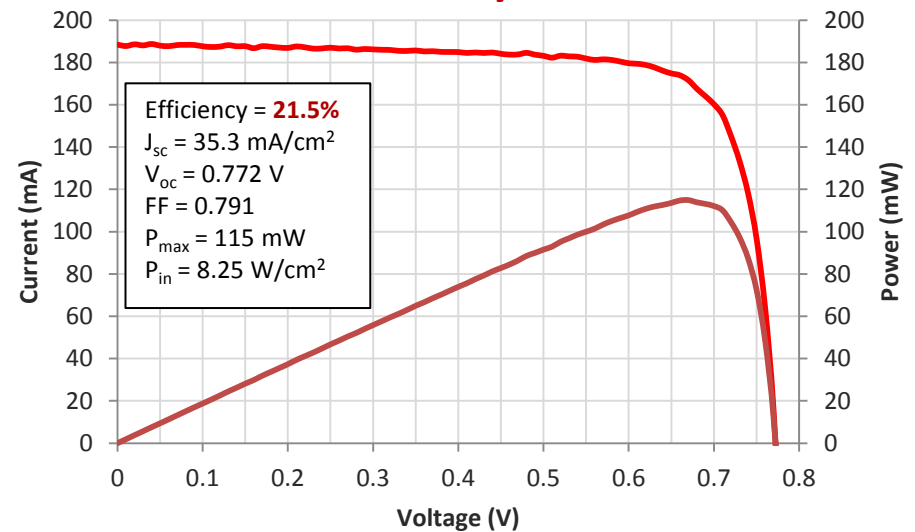




Single sun efficiency 15.9%



Maximum efficiency 21.5% at 82.5x

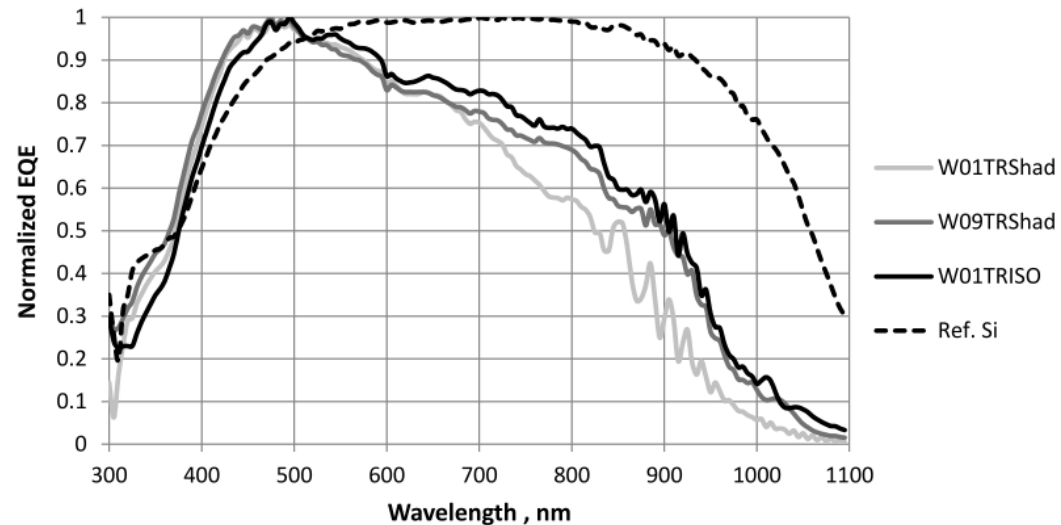
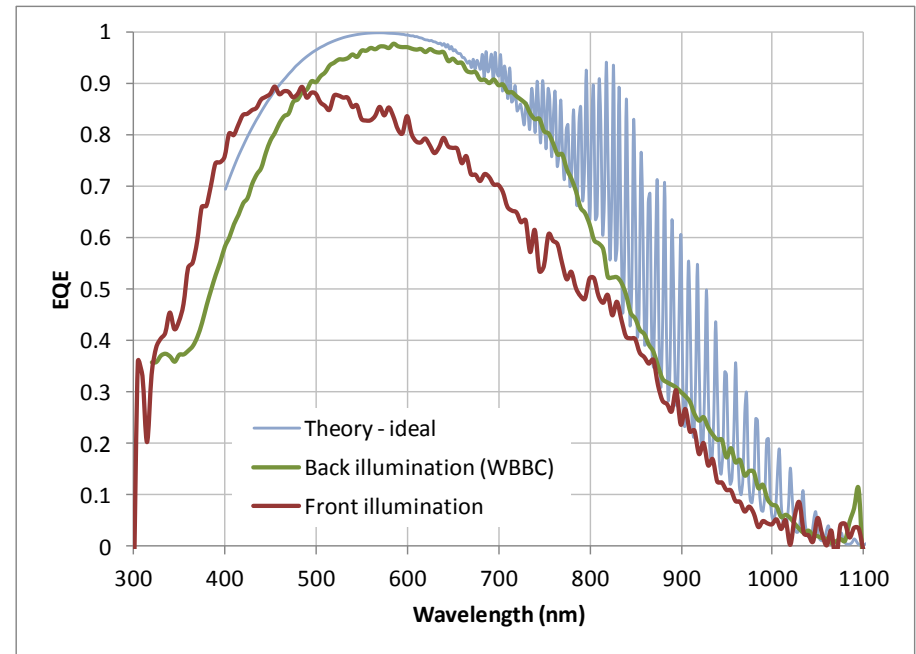


- Layer transfer cell with
 - 25um silicon layer
 - Backside texturing
 - Back reflector with integrated diffraction grating
- Measurements verified by SUNLab (Ontario)



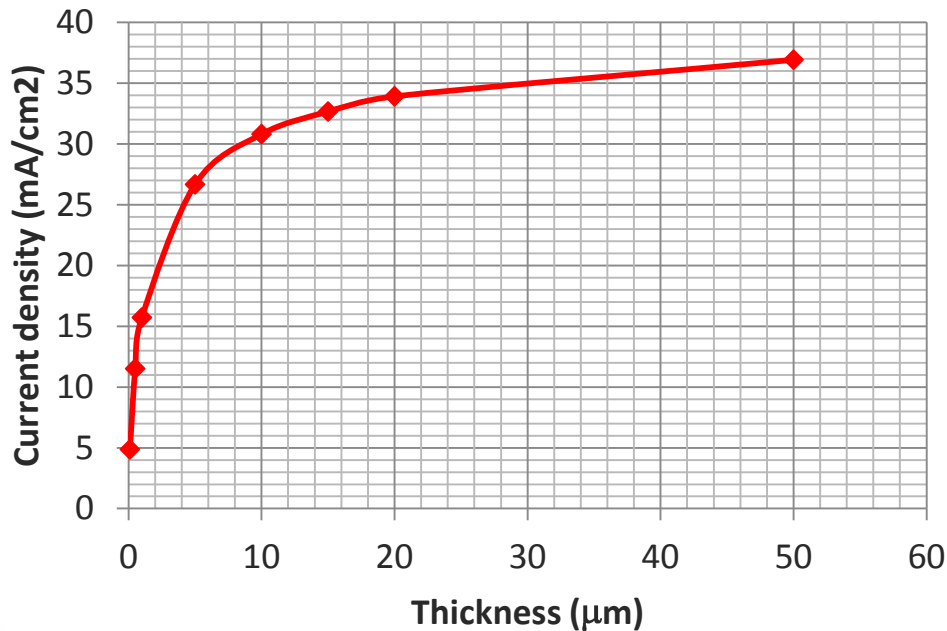
Results

- External quantum efficiency
 - Excellent blue-green photon capture and collection
 - Near 100% EQE for 550-650nm wavelengths (peak of solar photon flux)
 - Significantly increased QE at red and IR wavelengths from incident surface texturing





Current density vs silicon thickness



- Optimum thickness 20-50 µm
- Maximising V_{oc} (thin) while capturing as many photons as possible (thick)



Next steps

- Cost reduction of post-growth layer transfer
- Efficiency improvements
 - Improved light trapping
 - Improved (MIS) contacts
 - Surface plasmon resonances
 - Multi-junction cells
 - Optimized cell design



Thank you